### Silicon NPN Epitaxial

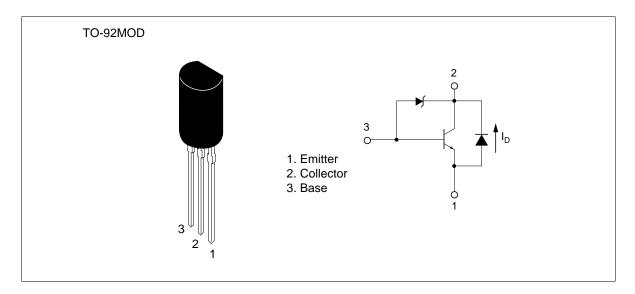
# **HITACHI**

ADE-208-1160 (Z) 1st. Edition Mar. 2001

### Application

Low frequency power amplifier

#### Outline





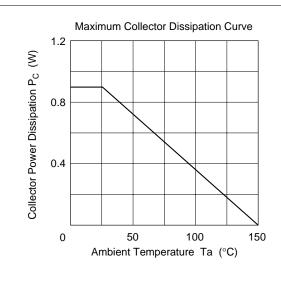
### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

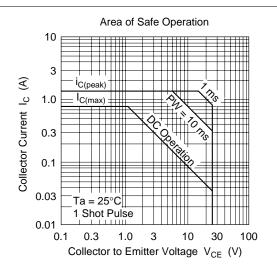
Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{\text{CBO}}$	25	V
Collector to emitter voltage	$V_{\text{CEO}}$	25	V
Emitter to base voltage	$V_{EBO}$	6	V
Collector current	I <sub>c</sub>	0.8	А
Collector peak current	ic <sub>(peak)</sub>	1.5	А
E to C diode forward current	I <sub>D</sub>	0.8	А
Collector power dissipation	P <sub>c</sub>	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

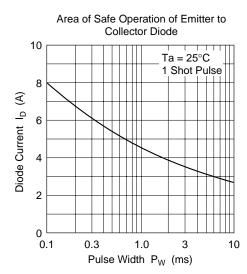
#### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

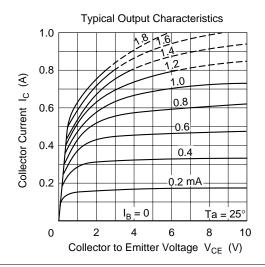
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	25	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	25	_	35	V	$I_{C} = 1 \text{ mA}, R_{BE} = \infty$
Collector to emitter sustaining voltage	$V_{\text{CEO(sus)}}$	25	_	35	V	$I_{C} = 0.8 \text{ A}, R_{BE} = \infty,$ L = 20  mH
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	V	$I_{E} = 10 \mu A, I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	0.2	μΑ	$V_{CB} = 20 \text{ V}, I_{E} = 0$
	I <sub>CEO</sub>	_	_	0.5	μΑ	V <sub>CE</sub> = 20 V, R <sub>BE</sub> = ∞
Emitter cutoff current	I <sub>EBO</sub>	_	_	0.2	μΑ	$V_{EB} = 5 \text{ V}, I_{C} = 0$
DC current transfer ratio	h <sub>FE</sub>	250	_	1200		$V_{CE} = 2 \text{ V}, I_{C} = 0.1 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.3	V	$I_{\rm C} = 0.8 \text{ A}, I_{\rm B} = 80 \text{ mA}^{*1}$
E to C diode forward voltage	$V_{\scriptscriptstyle D}$			1.1	V	$I_D = 0.8 A^{*1}$

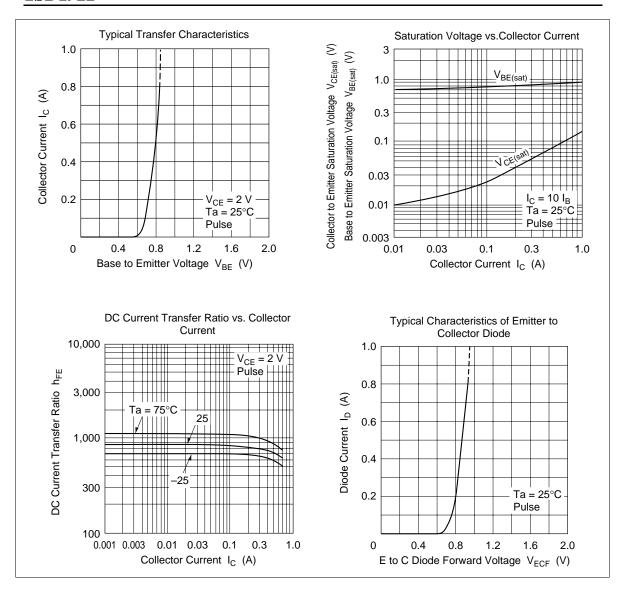
Note: 1. Pulse test

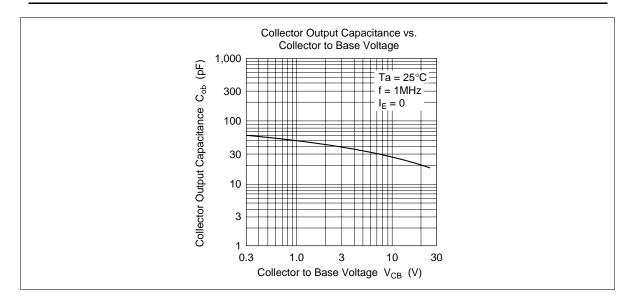




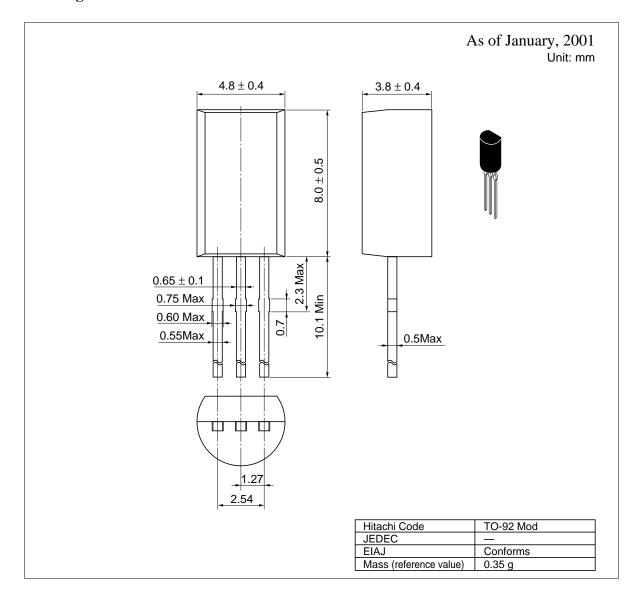








#### **Package Dimensions**



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